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AMENDMENT TRANSMITTAL LETTER (Large Entity)				Docket No. 11948.0021	
Applicant(s): Rajeev Joshi et al.					

Application No. 10/618,113	Filing Date July 11, 2003	Examiner David A. Zarnecke	Customer No. 27966	Group Art Unit 2829	Confirmation No. 8697
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Invention: **WAFER-LEVEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME**



COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	29 -	33 =	0	x \$50.00	\$0.00
INDEP. CLAIMS	7 -	8 =	0	x \$200.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account **50-0843**
 - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☐ Any patent application processing fees under 37 CFR 1.17.
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Signature

Dated: **6/16/05**

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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on <div style="text-align: center;"> (Date) </div>	
 Signature of Person Mailing Correspondence	
Erin Cowles Typed or Printed Name of Person Mailing Correspondence	

CC:



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Patent Application:
Rajeev Joshi et al.

Serial No.: 10/618,113

Filed: July 11, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 8697

Group Art Unit: 2829

Examiner: Zarnecke, David A.

Mail Stop Non-Final Response
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION UNDER
37 C.F.R. §§ 1.111 AND 1.116

In response to Notice of Non-Compliant Amendment mailed on June 9, 2005, and in further response to the Office Action mailed February 1, 2005, Applicant requests reconsideration of this application in light of the following amendments and remarks.

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Signed: 

6/16/2005